

## IN THE CLAIMS

Please amend Claim 15 to read as follows.

1-6. (Canceled)

7. (Previously Presented) A method of manufacturing an ink jet head having a substrate and a ceiling member joined to said substrate, wherein said substrate includes a plurality of energy generating elements for generating energy utilized to discharge ink, and wherein said ceiling member has a plurality of flow passage walls which define a plurality of flow passages when said substrate is joined to said ceiling member, the energy generated by said energy generating elements acting on the ink to discharge the ink through the plurality of flow passages, said method comprising the steps of:

providing a plurality of recessed portions in a surface on said substrate such that said plurality of recessed portions have a bottom surface located at a position which is lower than a position of a heat acting surface of said substrate; and

fitting said plurality of recessed portions to said flow passage walls of said ceiling member by applying a force to said ceiling member along a direction in which said plurality of energy generating elements are arranged, thereby aligning said flow passages with said energy generating elements.

8. (Previously Presented) The method of manufacturing an ink jet head according to claim 7, further comprising the step of:

providing a raised convex portion of material on a surface of said substrate

at an end portion thereof, wherein an area of said ceiling member corresponding to said convex portion is arranged such that said area of said ceiling member does not make contact with said convex portion.

9. (Previously Presented) The method of manufacturing an ink jet head according to claim 8, wherein said area of said ceiling member is provided within a dummy nozzle portion.

10. (Previously Presented) The method of manufacturing an ink jet head according to claim 8, wherein said convex portion is made of at least one of an epoxy and a silicone type photosensitive material.

11. (Previously Presented) A method of manufacturing an ink jet head having a substrate and a ceiling member joined to said substrate, wherein said substrate includes a plurality of energy generating elements for generating energy utilized for discharging ink, and wherein said ceiling member has a plurality of flow passage walls which define a plurality of flow passages when said substrate is joined to said ceiling member, the energy generated by said energy generating elements acting on the ink to discharge the ink through the plurality of flow passages, said method comprising the steps of:

providing a plurality of recessed portions in a surface on said substrate such that said plurality of recessed portions have a bottom surface located at a position which is lower than a position of a heat acting surface of said substrate; and

fitting said plurality of recessed portions to said flow passage walls of said

ceiling member by vibrating said substrate so that a force having at least a component acting in a direction in which said plurality of energy generating elements are arranged is applied to said ceiling member, thereby aligning said flow passages with said energy generating elements.

12. (Previously Presented) The method of manufacturing an ink jet head according to claim 11, further comprising the step of:

providing a raised convex portion of material on a surface of said substrate at an end portion thereof, wherein an area of said ceiling member corresponding to said convex portion is arranged such that said area of said ceiling member does not make contact with said convex portion.

13. (Previously Presented) The method of manufacturing an ink jet head according to claim 12, wherein said area of said ceiling member is provided within a dummy nozzle portion.

14. (Previously Presented) The method of manufacturing an ink jet head according to claim 12, wherein said convex portion is made of at least one of an epoxy and a silicone type photosensitive material.

15. (Currently Amended) The method of manufacturing an ink jet head according to claim 11, wherein said substrate is vibrated by vibrations having an amplitude which is smaller than a depth of one of said recessed portions formed in the surface on said substrate.

16-18. (Canceled)